

Diode

Emitter Controlled 4 Medium Power Technology
IDC15D120T8M

Data Sheet

Industrial Power Control



Table of Contents

Features and Applications.....	3
Mechanical Parameters.....	3
Maximum Ratings.....	4
Static and Electrical Characteristics	4
Further Electrical Characteristics	4
Chip Drawing.....	5
Revision History	6
Relevant Application Notes	6
Legal Disclaimer	7

Diode Chip in Emitter Controlled 4 Medium Power Technology

Features:

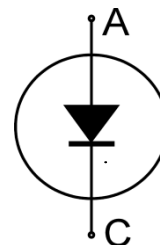
- 1200V Emitter Controlled 4 technology
110µm chip
- Soft, fast switching
- Low reverse recovery charge
- Small temperature coefficient

Recommended for:

- Low / medium power modules

Applications:

- Low / medium power drives



Chip Type	V_R	I_{FN}	Die Size	Package
IDC15D120T8M	1200V	25A	4.28mm x 3.40mm	Sawn on foil

Mechanical Parameters

Die size	4.28 x 3.40	mm ²
Area total	14.55	
Anode pad size	3.306 x 2.446	
Silicon thickness	110	µm
Wafer size	200	mm
Maximum possible chips per wafer	1890	
Passivation frontside	Photoimide	
Pad metal	3200nm AlSiCu	
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process	
Die bond	Electrically conductive epoxy glue and soft solder	
Wire bond	Al, ≤500µm	
Reject ink dot size	∅ 0.65mm; max 1.2mm	
Storage environment (<6 months)	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C
	for open MBB bags	Acc. IEC 62258-3; Section 9.4 Storage Environment.

Maximum Ratings

In general, from reliability and lifetime point of view, the lower the operation junction temperature and/or the applied voltage, the greater the expected lifetime of any semiconductor device.

Parameter	Symbol	Conditions	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^{\circ}\text{C}$	1200	V
Continuous forward current ¹	I_F		-	A
Maximum repetitive forward current ²	I_{FRM}		50	
Junction temperature	T_{vj}		-40...+175	$^{\circ}\text{C}$
Operating junction temperature	$T_{vj\text{ op}}$		-40...+150	$^{\circ}\text{C}$

Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Reverse leakage current	I_R	$V_R=1200\text{V}$	-	-	5.2	μA
Cathode-anode breakdown voltage	V_{BR}	$I_R=0.25\text{mA}$	1200	-	-	V
Forward voltage drop	V_F	$I_F=25\text{A}$	1.35	1.70	2.05	

Further Electrical Characteristics

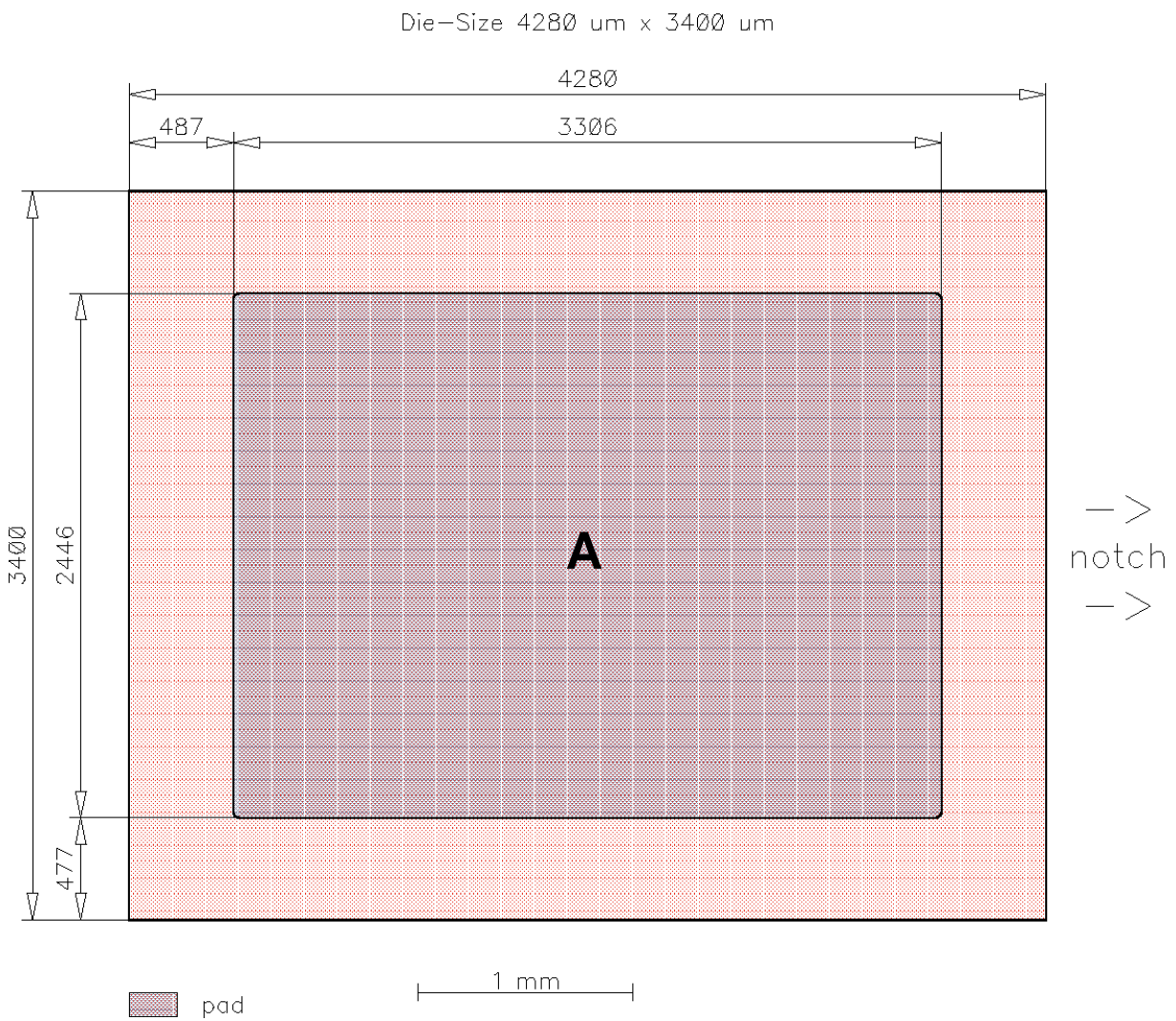
Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Application example	FP25R12U1T4	Rev. 2.0
---------------------	-------------	----------

¹ Depending on thermal properties of assembly.

² Not subject to production test - verified by design/characterization.

Chip Drawing



A = Anode pad



IDC15D120T8M

Bare Die Product Specifics

Test coverage at wafer level cannot cover all application conditions. Therefore it is recommended to test all characteristics which are relevant for the application at package level, including RBSOA and SCSOA.

Description

AQL 0.65 for visual inspection according to failure catalogue

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Revision History

Revision	Subjects (major changes since last revision)	Date
2.0	Final data sheet	22.08.2016

Relevant Application Notes



Published by
Infineon Technologies AG
81726 München, Germany
© Infineon Technologies AG 2016.
All Rights Reserved.

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (www.infineon.com).

Please note that this product is not qualified according to the AEC Q100 or AEC Q101 documents of the Automotive Electronics Council.

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

www.infineon.com

Published by Infineon Technologies AG